

**FEATURES**

- Wide angle of emission
- Metal package for heatsinking
- 50 mW output

All surfaces are gold plated. Dimensions are nominal values in inches unless otherwise specified.



**ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, $P_O$	$I_F = 300\text{mA}$	40	50		mW
Luminous Output	300mA		12		Lumens
Luminous Intensity	300mA, 2° FOV		4		Cd
Peak Emission Wavelength, $\lambda_P$	$I_F = 50\text{mA}$		620		nm
Spectral Bandwidth at 50%, $\Delta\lambda$			25		nm
Half Intensity Beam Angle, $\theta$			110		Deg
Forward Voltage, $V_F$	$I_F = 300\text{mA}$		2.2	2.5	Volts
Reverse Breakdown Voltage, $V_R$	$I_R = 10\mu\text{A}$	2	5		Volts
Rise and Fall Time, $t_r, t_f$	$I_F = 50\text{mA}$		100		nsec

**ABSOLUTE MAXIMUM RATINGS AT 25°C CASE**

Power Dissipation <sup>1</sup>	750mW
Continuous Forward Current <sup>1</sup>	300mA
Reverse Voltage	2V
Lead Soldering Temperature (1/16" from case for 10sec)	260°C

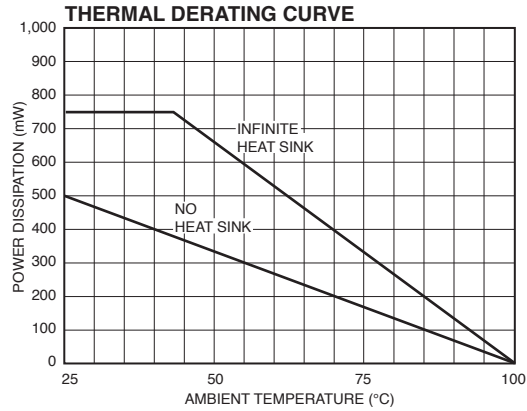
<sup>1</sup> Derate per appropriate thermal dissipation value above 25°C.

**THERMAL PARAMETERS**

Storage and Operating Temperature Range	-40°C TO 100°C
Maximum Junction Temperature	100°C
Thermal Dissipation Junction-Case	75°C/W Typical
Thermal Dissipation Junction-Air	145°C/W Typical

<sup>1</sup> Derate per appropriate thermal dissipation value above 25°C.

MAXIMUM RATINGS



TYPICAL CHARACTERISTICS

